Graphene-Based Reversible Nano-Switch/Sensor Schottky Diode

This device can extend applications of nanoelectronics to embedded bio-medical devices and explosive-detection devices.

John H. Glenn Research Center, Cleveland, Ohio

This proof-of-concept device consists of a thin film of graphene deposited on an electrodized doped silicon wafer. The graphene film acts as a conductive path between a gold electrode deposited on top of a silicon dioxide layer and the reversible side of the silicon wafer, so as to form a Schottky diode. By virtue of the two-dimensional nature of graphene, this device has extreme sensitivity to different gaseous species, thereby serving as a building block for a volatile species sensor, with the attribute of having reversibility properties. That is, the sensor cycles between active and passive sensing states in response to the presence or absence of the gaseous species.

In addition, because of the sensitivity and diode properties, the device can be used as a switch where its operational stages (i.e., open/closed, on/off) could be controlled by a given gaseous species. Consequently, this proof-of-concept has great potential as a building block for implementation of a switch/sensor device for harsh, embedded, or enclosed environments (e.g., the human body, space-based habitats, airplanes, subways, etc.) where the longevity and reusability of the circuit are critical for reliable operation.

The sensing performance of this device has been experimentally tested in an ambient atmosphere, as well as under an ammonia gas (NH₃) atmosphere. The experimental data demonstrate the dual switching/sensing nature of the nano Schottky diode, hence, the acronym nanoSSSD. Accordingly, the reversible behavior makes the diode suitable for nano-sensing devices intended for applications where access to the sensor, and its potential replacement opportunities, are limited.

The graphene-based nanoSSSD consists of an n-doped or p-doped silicon substrate with a 200-nm thermally grown layer of silicon dioxide (SiO₂). The diode can be turned on and off by applying DC voltage between the top metal electrode and the silicon substrate.

Inductive Non-Contact Position Sensor

John F. Kennedy Space Center, Florida

Optical hardware has been developed to measure the depth of defects in the Space Shuttle Orbiter’s windows. In this hardware, a mirror is translated such that its position corresponds to the defect’s depth, so the depth measurement problem is transferred to a mirror-position measurement problem. This is preferable because the mirror is internal to the optical system and thus accessible. Based on requirements supplied by the window inspectors, the depth of the defects needs to be measured over a range of 200 microns with a resolution of about 100 nm and an accuracy of about 400 nm. These same requirements then apply to measuring the position of the mirror, and in addition, since this is a scanning system, a response time of about 10 ms is needed.

A market search was conducted and no sensor that met these requirements that also fit into the available housing volume (less than one cubic inch) was found, so a novel sensor configuration was constructed to meet the requirements. This new sensor generates a nearly linearly varying magnetic field over a small region of space, which can easily be sampled, resulting in a voltage proportional to position.

Experiments were done with a range of inductor values, drive voltages, drive frequencies, and inductor shapes. A rough mathematical model was developed for the device that, in most aspects, describes how it operates and what electrical parameters should be chosen for best performance. The final configuration met all the requirements, yielding a small rugged sensor that was easy to use and had nanometer-resolution over more than the 200-μm range required.

The inductive position sensor is a compact device (potentially as small as 2 cm³), which offers nanometer-position resolution over a demonstrated range of nearly 1 mm. One of its advantages is the simplicity of its electri-
High-Temperature Surface-Acoustic-Wave Transducer

This thin, high-temperature-resistant sensor is designed for crack inspections.

John H. Glenn Research Center, Cleveland, Ohio

Aircraft-engine rotating equipment usually operates at high temperature and stress. Non-invasive inspection of microcracks in those components poses a challenge for the non-destructive evaluation community. A low-profile ultrasonic guided wave sensor can detect cracks in situ. The key feature of the sensor is that it should withstand high temperatures and excite strong surface wave energy to inspect surface/subsurface cracks. As far as the innovators know at the time of this reporting, there is no existing sensor that is mounted to the rotor disks for crack inspection; the most often used technology includes fluorescent penetrant inspection or eddy-current probes for disassembled part inspection.

An efficient, high-temperature, low-profile surface acoustic wave transducer design has been identified and tested for nondestructive evaluation of structures or materials. The development is a Sol-Gel bismuth titanate-based surface-acoustic-wave (SAW) sensor that can generate efficient surface acoustic waves for crack inspection. The produced sensor is very thin (submillimeter), and can generate surface waves up to 540 °C. Finite element analysis of the SAW transducer design was performed to predict the sensor behavior, and experimental studies confirmed the results.

One major uniqueness of the Sol-Gel bismuth titanate SAW sensor is that it is easy to implement to structures of various shapes. With a spray coating process, the sensor can be applied to surfaces of large curvatures. Second, the sensor is very thin (as a coating) and has very minimal effect on airflow or rotating equipment imbalance. Third, it can withstand temperatures up to 530 °C, which is very useful for engine applications where high temperature is an issue.

This work was done by Xiaoliang Zhao of Intelligent Automation, Inc. and Bernhard R. Tittmann of Pennsylvania State University for Glenn Research Center. Further information is contained in a TSP (see page 1).

Inquiries concerning rights for the commercial use of this invention should be addressed to NASA Glenn Research Center, Innovative Partnerships Office, Attn: Steven Fedor, Mail Stop 4–8, 21000 Brookpark Road, Cleveland, Ohio 44135. Refer to LEW-18547-1.